

Filename: PMP5670REVA-1 BOM.xls

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PMP5670REVA-1 BOM

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C4	100pF	Capacitor, Ceramic, 50V, C0G, 5%	0603	Std	Std
1	C5	100pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C9	6.8nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C10	220pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C12	100nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C15	22uF	Capacitor, Aluminum, SMT, 100V, 20%	8x10mm	EEVFK2A220P	Panasonic
1	C16	47uF	Capacitor, Aluminum, 35V, 20%	0.260 x 0.276 inch	EEEFK1V470P	Panasonic
1	C100	10uF	Capacitor, Ceramic, 16V, X5R, 15%	1210	Std	Std
2	C1-2	4.7uF	Capacitor, Ceramic, 50V, X7R, 10%	1210	Std	Std
2	C13-14	470nF	Capacitor, Ceramic, 100V, X7R, 10%	1210	Std	Std
4	C6-8 C11	100nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	D1	10BQ060	Diode, Schottky, 1A, 60V	403A	10BQ060	Vishay
1	D3	12V	Diode, Zener, 12V, SOT23	SOT23	BZX84C12LT	On Semi
2	J1-2		Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25"	ED1514	OST
1	L1	33uH	Inductor, SMT, 93mOhm, 2.3A sat, 1.6A rms	0.402 x 0.394 inch	MSS1038-333MLC	Coilcraft
1	Q1	SI4850EY	MOSFET, Nch, 60V, 8.5A, 22mOhm	SO8	SI4850EY	Vishay
1	Q2	MMBT2222	Bipolar, NPN, 30V, 600mA	SOT23	MMBT2222LT1	ON Semi
1	Q3	FZT655	Bipolar, NPN, 150V, 1A	SOT223	FZT655	Zetex
1	R1	0.33	Resistor, Chip, 1/4 watt, 1%	1206	Std	Std
1	R2	1.00k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R3	20.0k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R5	76.8k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R10	6.34k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R13	11.5k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R14	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R100	49.9k	Resistor, Chip, 1/10W, 1%	0805	Std	Std
2	R11-12	32.4k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R4 R7	10.5k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R8-9	100k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
5	TP1-4 TP7		Test Point, Red, 1mm	0.038	240-345	Farnell
2	TP5-6		Test Point, Black, 1mm	0.038"□240-333"	240-333	Farnell
1	U1	UCC2813-0	IC, Current-mode PWM, Von = 7.2V	SO8	UCC2813-0D	Texas Instruments
1	U2	TLV271	IC, Op-Amp, Rail-to-rail, 600uA per Ch	DBV (SOT23-5)	TLV271DBV	Texas Instruments

Notes:

1. These assemblies are ESD sensitive, ESD precautions shall be observed.
2. These assemblies must be clean and free from flux and all contaminants.
Use of no clean flux is not acceptable.
3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
4. Ref designators marked with an asterisk (***) cannot be substituted.
All other components can be substituted with equivalent MFG's components.

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